SUSS MICROTEC
INVESTOR PRESENTATION

February 2021

DISCLAIMER

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AGENDA

I. **Overview**

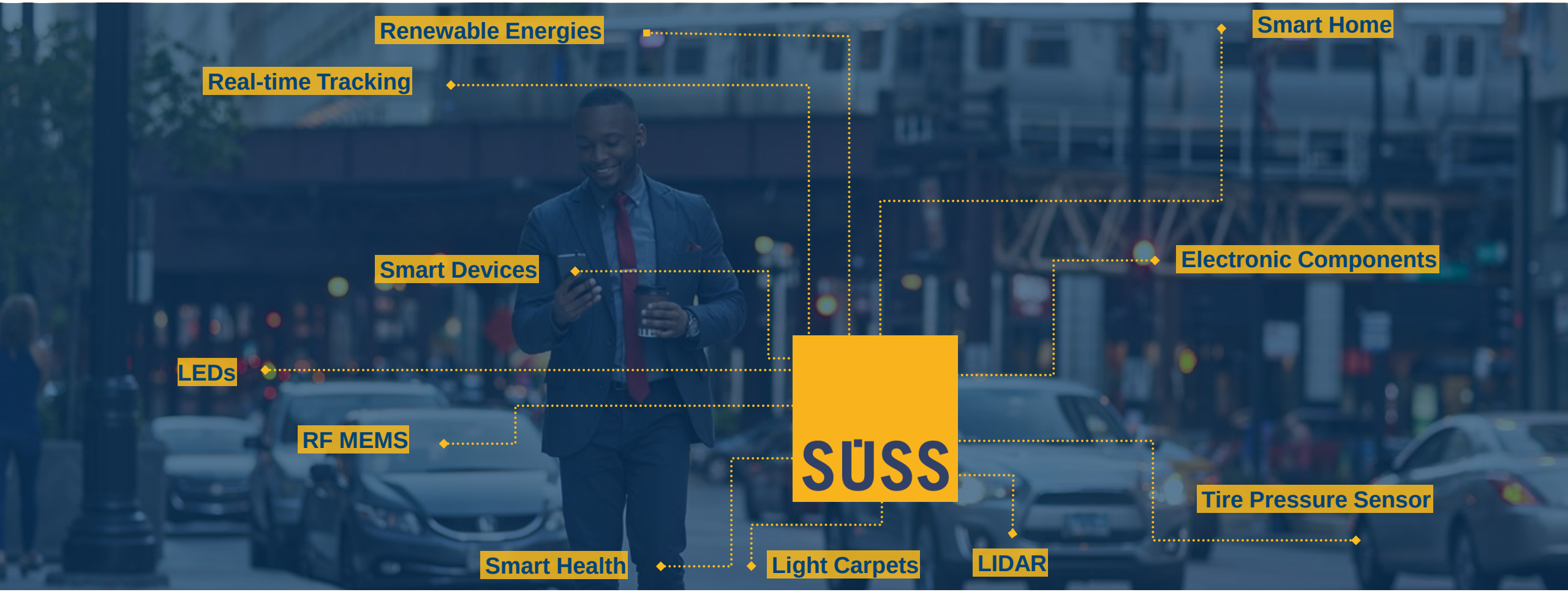
II. Strategy SUSS 2025

III. 9M and Preliminary Year End Results 2020

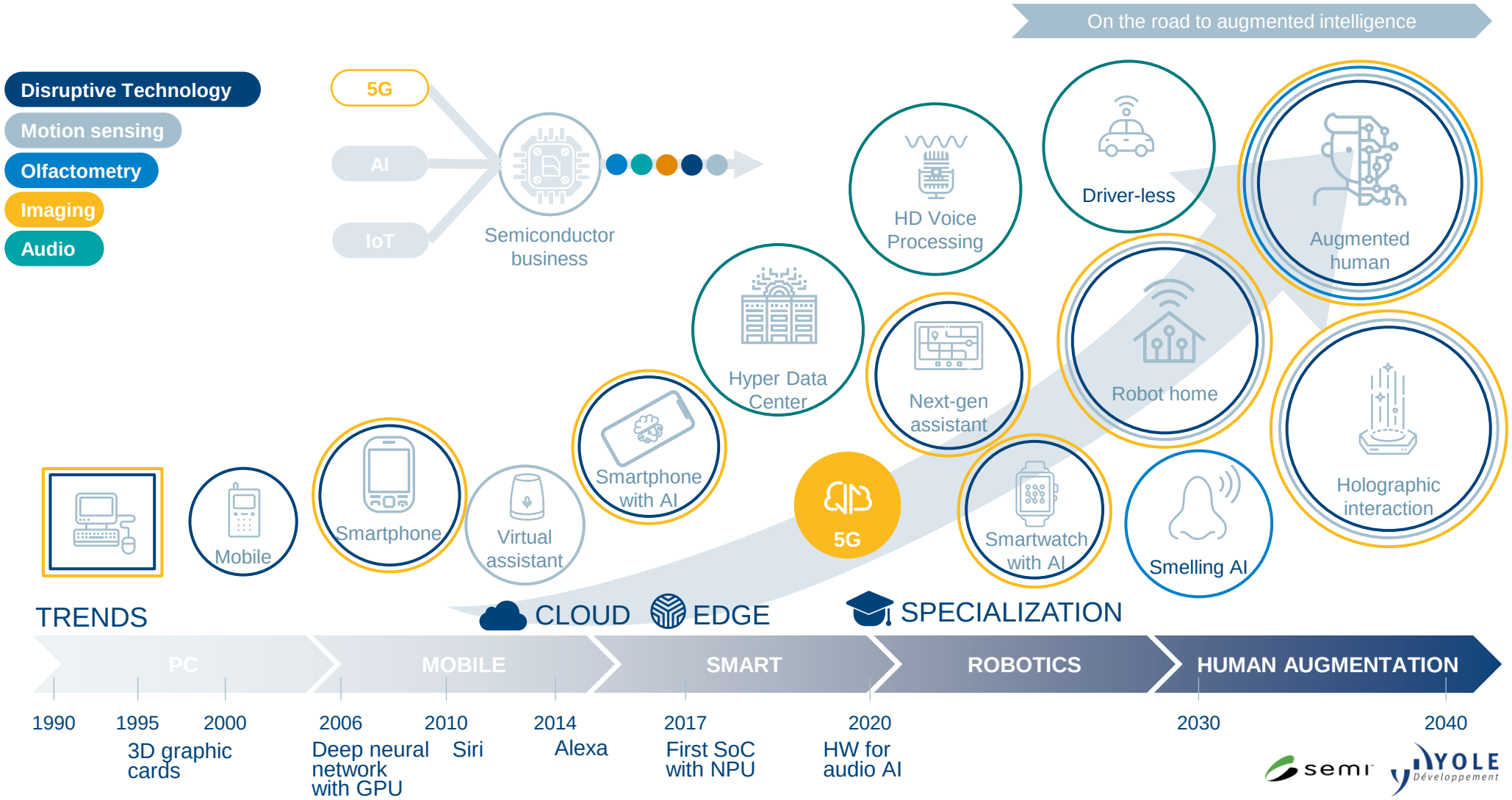
IV. Outlook

SUSS MICROTEC TAKES PART OF ALL ELECTRONIC MEGA TRENDS

SUSS MICROTEC BENEFITS FROM ALL ELECTRONIC MEGA TRENDS



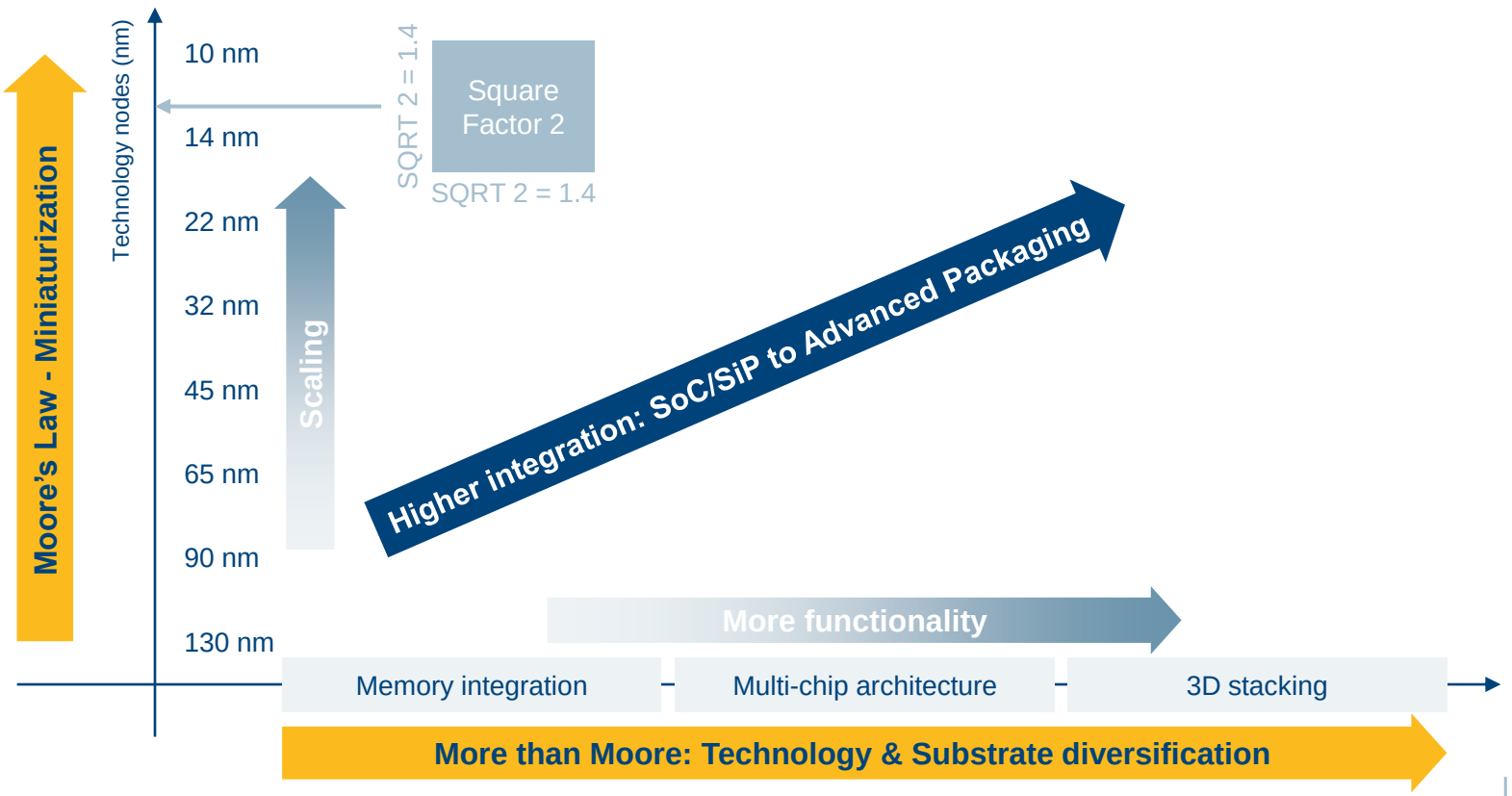
ROADMAP OF ELECTRONIC MEGA TRENDS



MORE THAN MOORE TECHNOLOGIES GO BEYOND TRANSISTOR SCALING (MOORE'S LAW)

More than Moore technologies, including advanced packaging, enable the underlying requirements of all the mega trends:

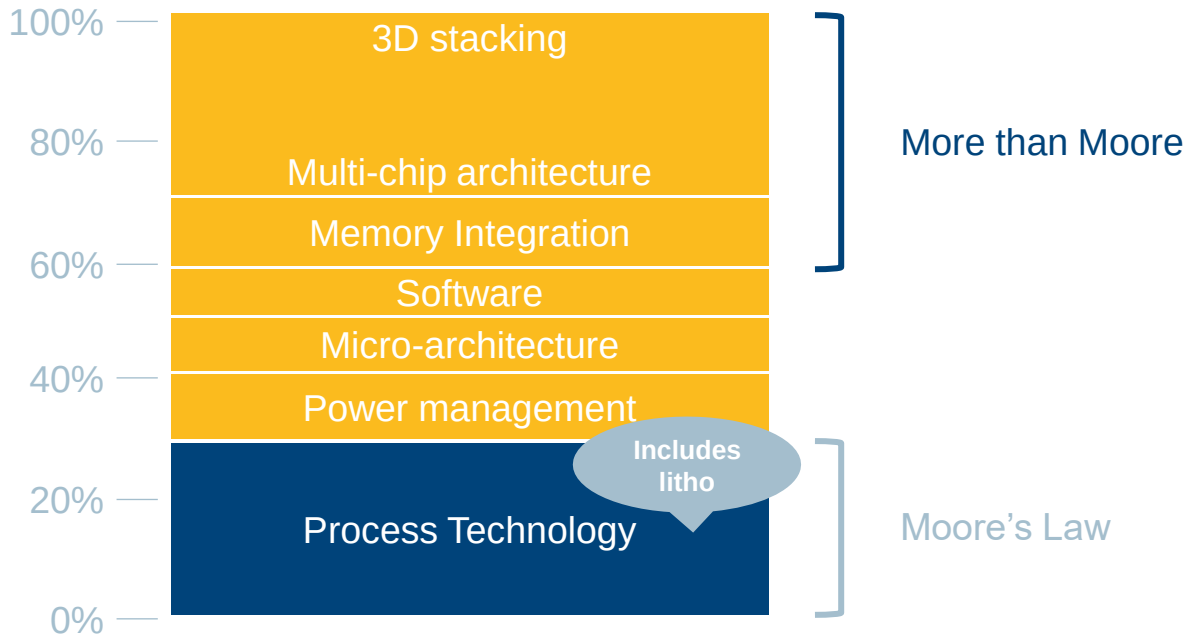
- Increase in computing power
- Optimization of power consumption
- Advanced substrates
- Miniaturization



AN IMPORTANT NEED TO DEVELOP MORE THAN MOORE TECHNOLOGIES

ASML, the most valuable equipment manufacturer and main enabler of Moore's Law, acknowledges the need to develop Moore than More technologies

Improvement opportunities for next decade

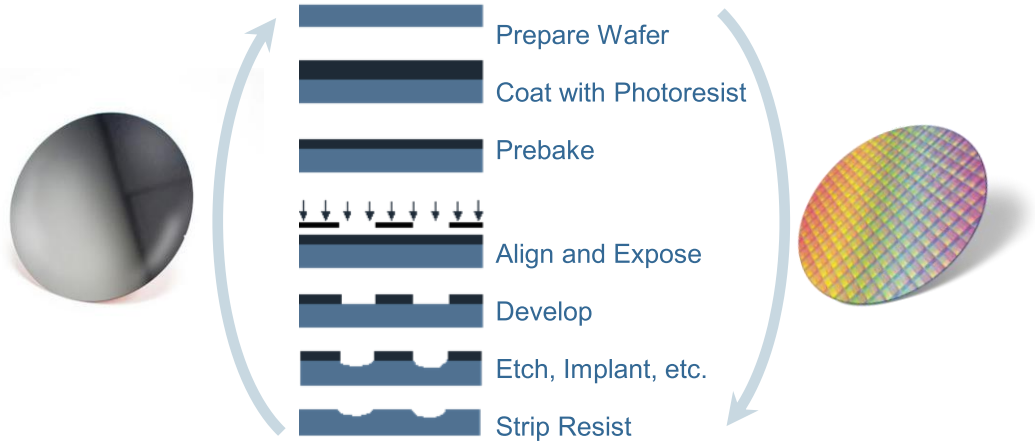


Source: ASML

ENABLING THE MOST VALUABLE SEMICONDUCTOR PROCESSES

“Moore’s Law”

Front-end wafer fab



600 – 1000 steps, cycle time > 3 month

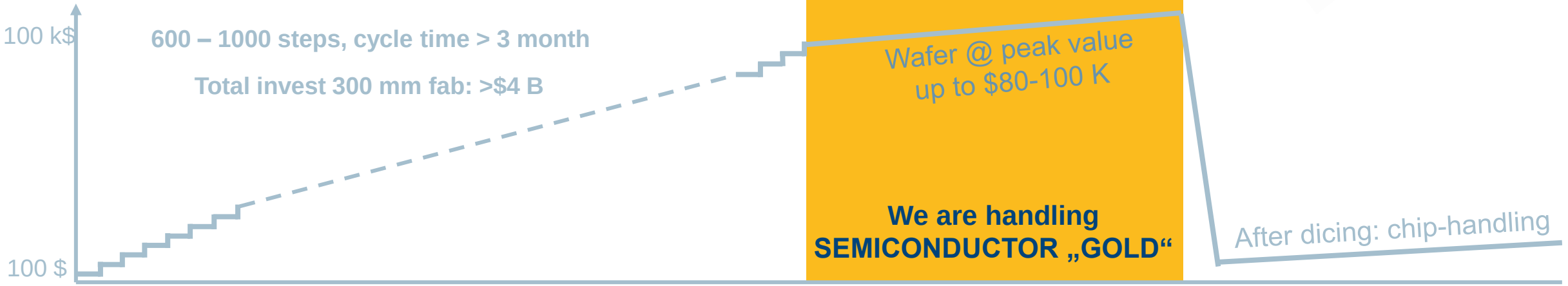
Total invest 300 mm fab: >$4 B

“More Than Moore”

Wafer-level packaging

SUSS field of activity

Supporting key processes:
Coating
Lithography
Bonding
Cleaning
etc.



We are handling SEMICONDUCTOR „GOLD“

1/10 of a percent yield improvement is real big money!

SUSS WELL POSITIONED

‘More than Moore’ market

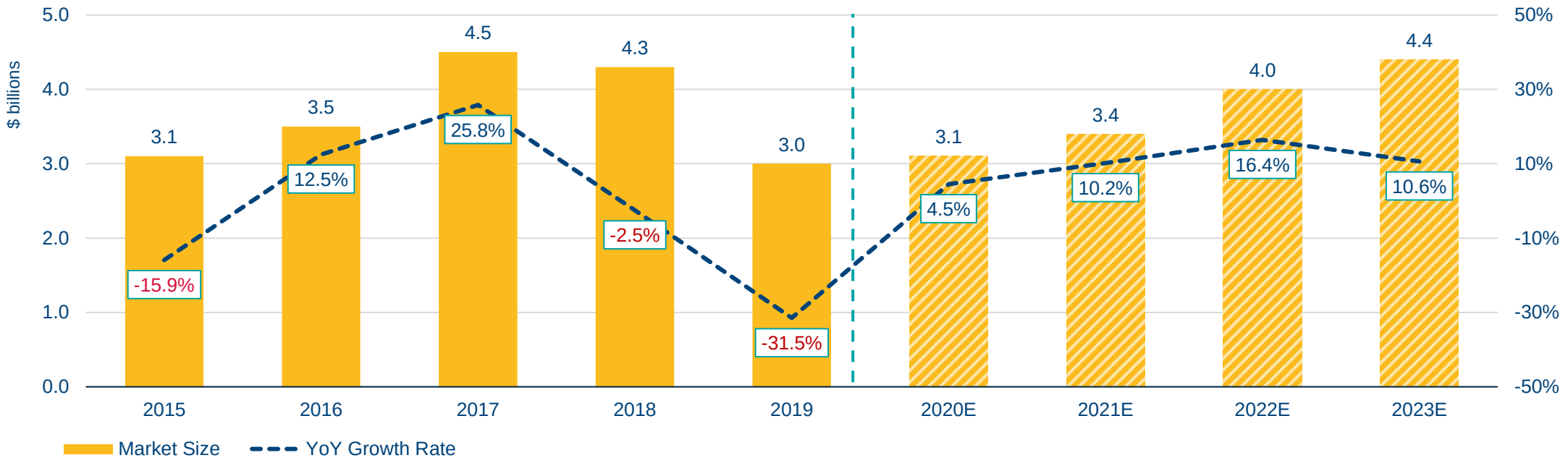
- More-than-More to capture an increasing value of equipment spending
- Many customers have very specific process needs → higher degree of customization and close relationship
- High valued wafer to be handled! Most important: No wafer losses, minimize yield loss
- Optimized process steps per application, tailored equipment per application needed

Consequences for SUSS

- **Extremely well positioned with a diversified range of equipment for ‘More than Moore’ applications**
- **High degree of customization as processes are different at each customer**
- **SUSS is known for reliability, efficiency and best-in-class performance**

ENTERING IN A STRONG UP-CYCLE

Assembly Equipment Market

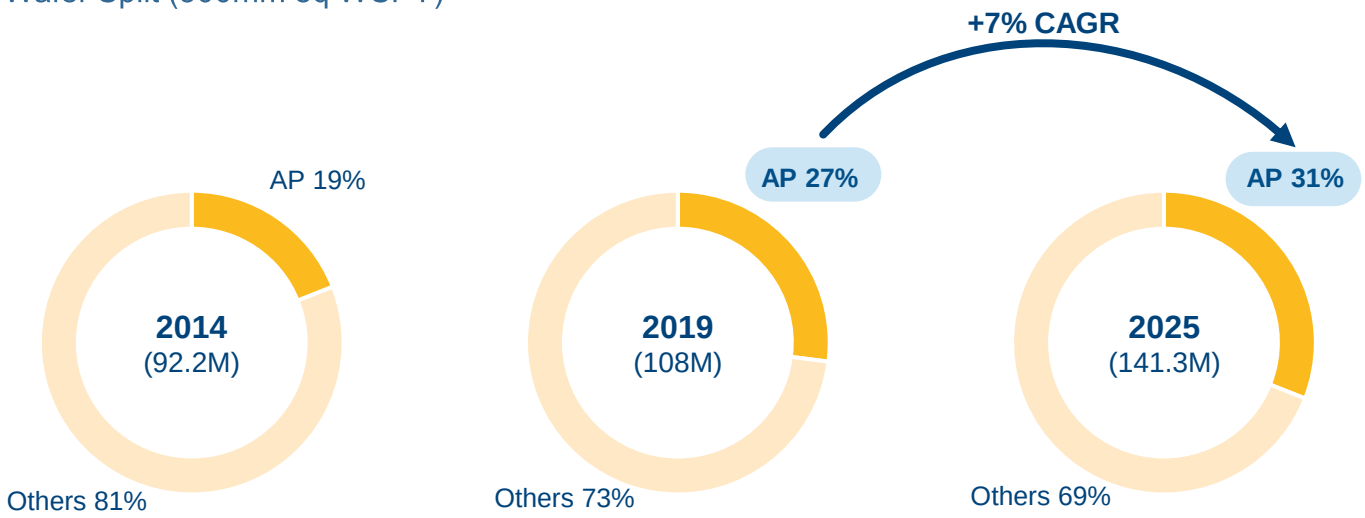


Source: VLSI September 3, 2020

USE OF MTM TECHNOLOGIES IS GROWING FAST

- In terms of 300mm eq wafers, traditional packaging still dominates with almost 75% of the total market.
- However, Advanced Packaging is continuously increasing its share of wafers and its market share increases from ~27% in 2019 to 31% in 2025.

Advanced Packaging Overview 2014 -2025
Wafer Split (300mm eq WSPY)



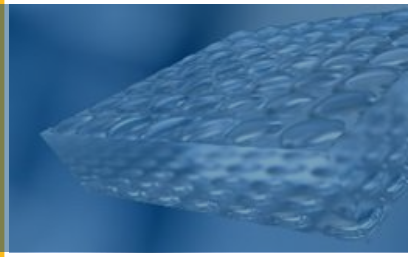
Why do manufacturers need advanced packaging?

- It enables to create complex modules with a relatively small footprint
- Complementary solutions to node scaling are needed to further increase performance per watt

Multiple short and mid term drivers

- 3D sensing
- 5G smartphones
- AI and HPC applications
- Mini-LED and Micro-LED display technologies

BROAD PRODUCT PORTFOLIO FOR DIFFERENT SEGMENTS AND MARKETS

SEGMENTS	‘Moore’s Law’ Frontend	‘More than Moore’ FRONTEND AND BACKEND			Specials
	Photomask Processing	Lithography		Wafer Bonder	Microoptics
					
PRODUCTS	Photomask Equipment	Exposure Systems	Coater / Developer Injekt Printing	Bonding Systems	Micro optical Components
PROCESS STEPS	Photomask Cleaning	Proximity Exposure (Mask Aligner)	Coating Developing	Boning Alignment	Imprint – Applications
	Wafer Cleaning for MEMS	Imprinting	Injekt Printing	Permanent Bonding Temporary Bonding Debonding Metrology	
		Metrology	Metrology		

SUSS MicroTec

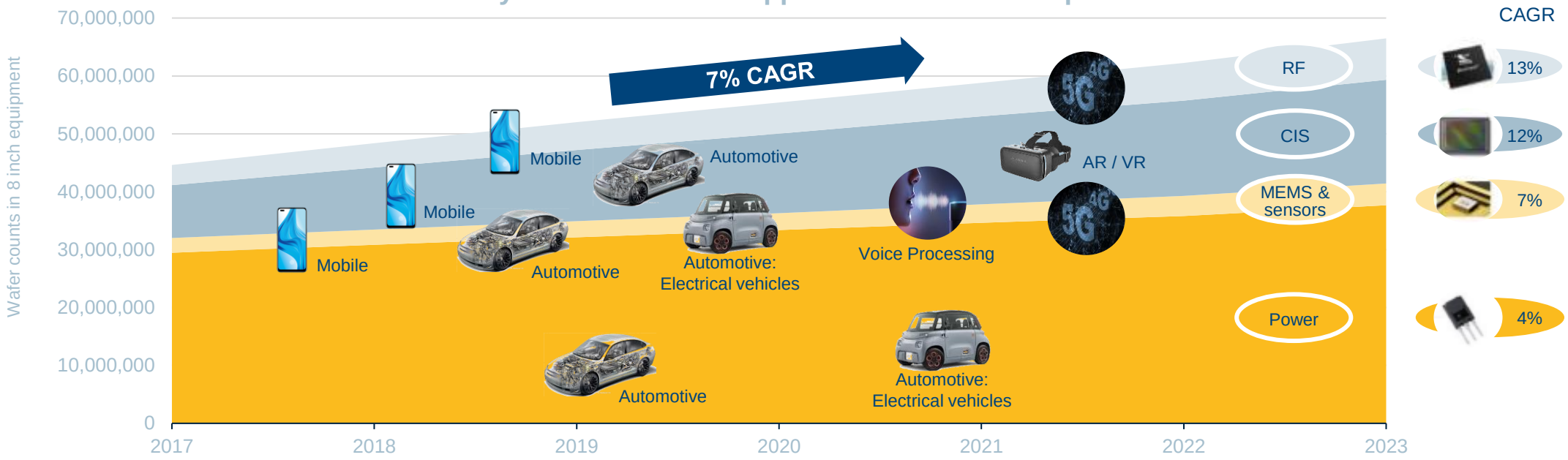
SUSS’ focus for further growth

WAFER BONDING IS A HIGHLY ATTRACTIVE ENDMARKT

- 2.5D and 3D requires temporary bonding for wafer thinning as well as D2W or W2W bonding
- D2W bonding enables heterogeneous integration, high yield is achieved by stacking known good dies (KGD)
- Hybrid bonding will be the main enabler for pitch scaling (TSV and µbump → Cu/Cu interconnects = hybrid bonding)
  - Used for the latest generation of CMOS image sensors since 2017
  - Will be used for other new 3D devices by IDMs and foundries
- Equipment market is forecasted to grow at a CAGR (2018-25) of ~25% by Yole Développement

Overall wafer demand for More than Moore devices

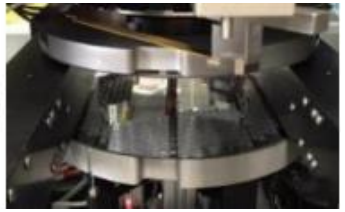
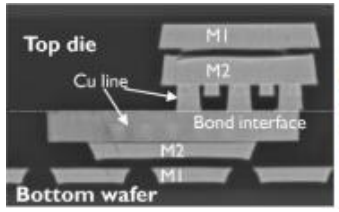
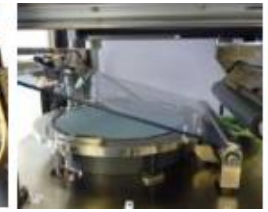
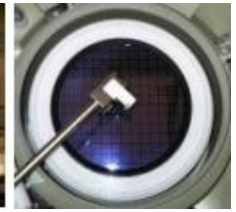
Breakdown by More than Moore application – in 8 inch eq



Source: Yole (2018, 2019)

BONDING PRODUCT PORTFOLIO

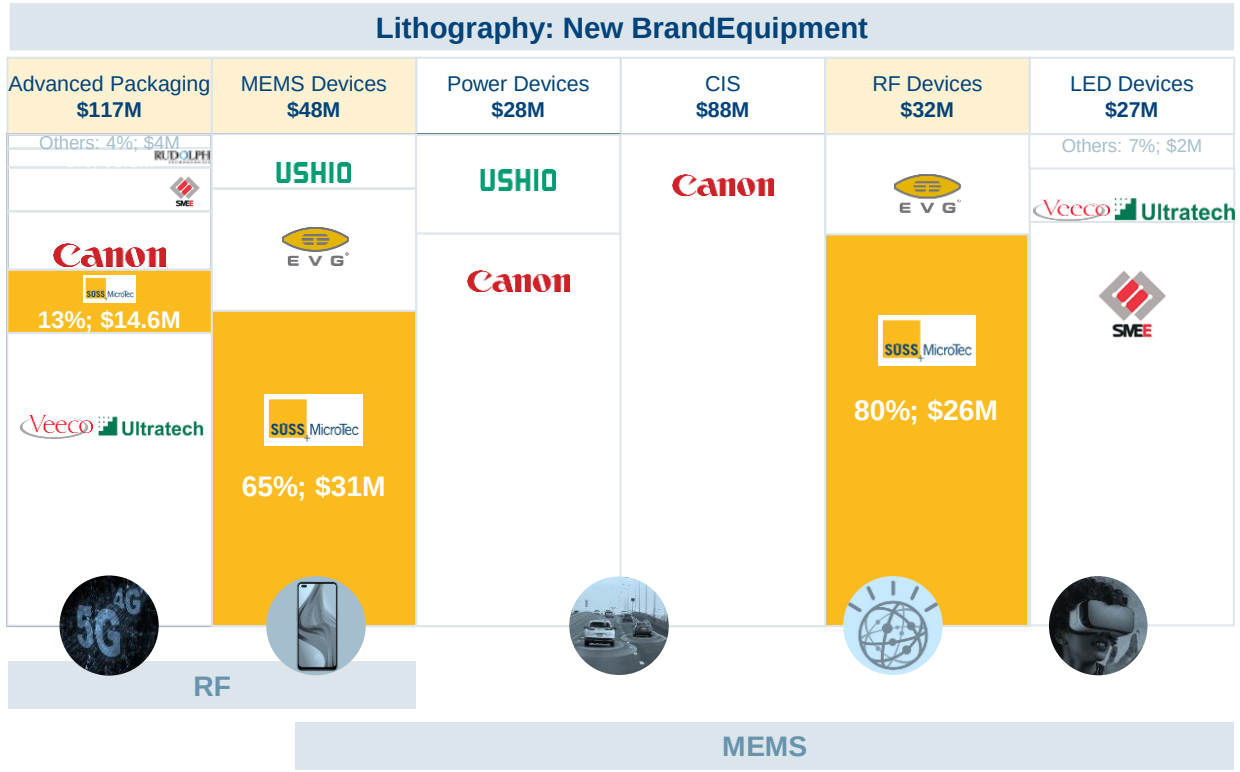
Business Unit Bonder

	More than Moore – MEMS and related			More than Moore – 2.5D and 3D				
								
	Semi-Automated Bonders		**Automated Permanent Bonders**		**Automated Temporary Bonders, Debonders and Cleaners**			
								
	SB6/8 Gen2 (20kN)	XB8 (100kN)	XBS200 W2W Bonder	XBS300 W2E / collective D2W Bonder	XBS300 Temporary Bonder	XBS300 Gen2 Debonder (mechanical / laser) and Cleaner		
Comment / USP	Large installed base Supports all traditional processes	Supports new high force / high-end processes	Fixture-less aligned wafer handling for best cost of ownership	>100nm overlay to support pitch scaling trend in hybrid bonding	Large installed base with ~40-50%[1] market share for 2.5D and 3D memory Technology enabler applications such as CIS, FO-WLP Started transition from mechanical to laser debonding for next generation devices			

[1] SUSS internal estimation

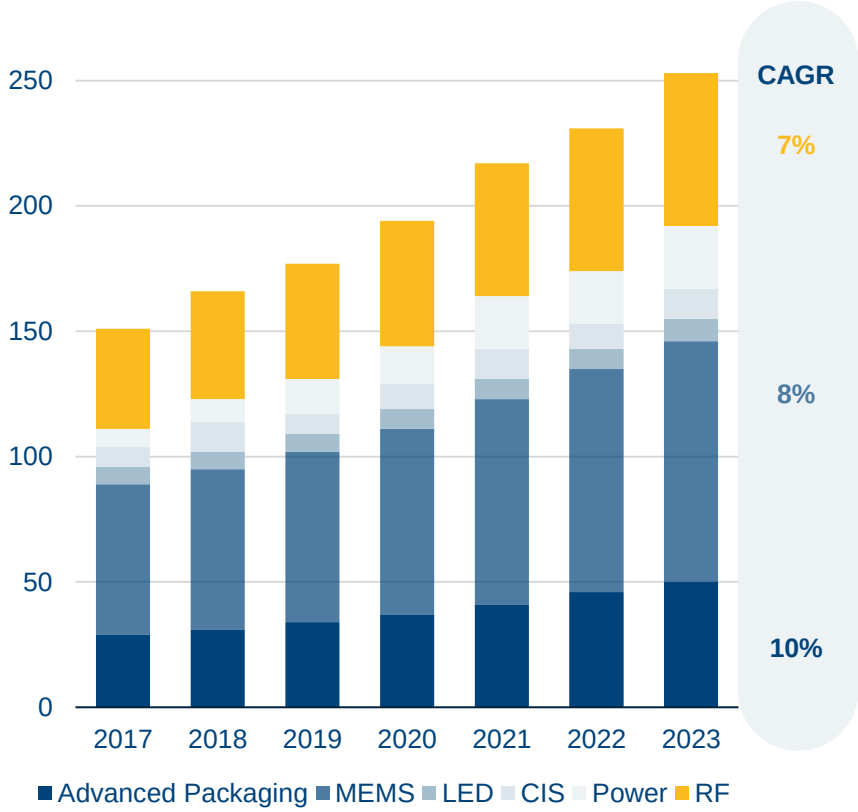
FAVORABLE LITHOGRAPHY MARKET ENVIRONMENT FOR SUSS

- Demand for “More than Moore” equipment is expected at CAGR of 7%-10%
- SUSS Exposure solutions have a dominant share for MEMS and RF devices
- Target to expand share in Advanced Packaging with Direct Write Projection



New-brand Lithography equipment market (nr. of tools)

Split by More than Moore device



Source: Yole (2018, 2019)

LITHOGRAPHY PRODUCT PORTFOLIO

SUSS Exposure Systems

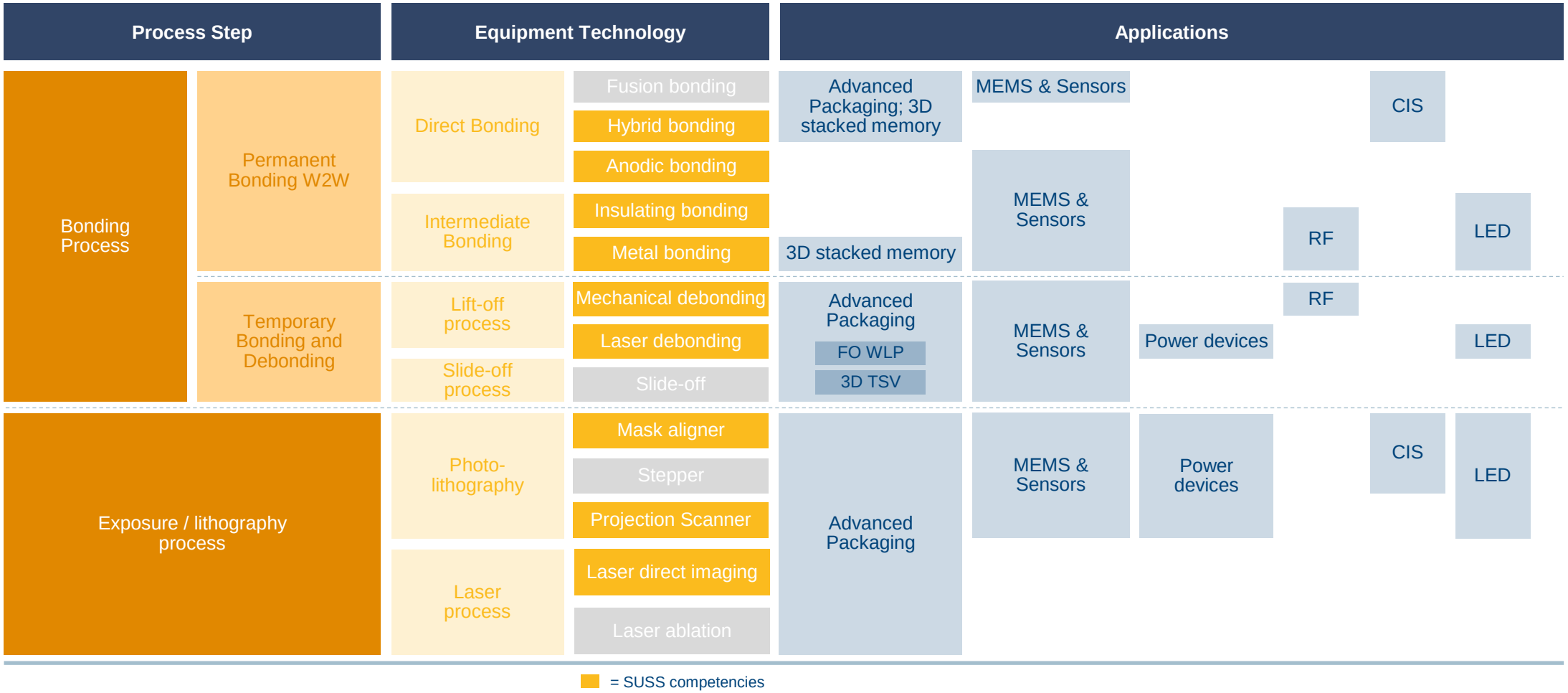
	Semi-Automated Aligners	Automated Aligners			Imprint	Metrology
	 MABA Gen 4 MABA Gen 5 Pro MABA Gen5	 MA12	 MA150	 MA200	 MA300	 XLC200 (coming soon)	
Comment / USP	Large install base, very versatile	Only offer in the market. Used for special More than Moore	Very high throughput, Linear transport, For cost-sensitive applications	Flagship product. Large install base, very versatile Overlay < 1um	Only offer in market. Used for Advanced Packaging with less challenging requirements	Development targeted for HVM applications in both markets, micro-imprint and nano-imprint. Strong process focus together with SMO	DSM is dedicated offering for back-side alignment processes. Modules integrated SUSS systems for smart manufacturing control

PACKAGING TECHNOLOGIES OVERVIEW ➡ MTM-APPLICATION

ARCHITECTURE		WIRE BOND	FLIPPED DIE	EMBEDDED DIE	2.5D	3D	EMERGING
		Traditional Packaging	Advanced Packaging				
SUBSTRATE TYPES	IC Substrate (Organic)		FC BGA EMIB (Intel) LSI (TSMC)		Si Interposers CoWoS (TSMC) Foveros (Intel)	3DS TSV (Samsung)	SoIC in CoWoS – SoC Hybrid Bonding (TSMC)
			FC CSP	CO-EMIB (Intel)		HBM TSV (Samsung) (SK Hynix)	Production in 2021
		WB CSP WB BGA	FC SiP Metal Shielding (JCET)	Embedded Die / Passives (SEMCO)		NAND TSV (Toshiba) Production after 2025	Embedded Multi-Die / Passives (JCET)
		BOC	Fan-Out on Substrate inFO_oS (TSMC) FoCOS (ASE)	ePLP / FOPLP (Samsung)			
	No Substrate	COB	Fan-Out inFO_PoP Fan-Out eWLB/M-series Fan-In (WLCSP)			Cu-Cu Hybrid Bonding – WoW (SONY) TSV, after bonding – WoW (SONY)	SoIC in Fan-Out – SoC Hybrid Bonding (TSMC) Production after 2021
	Ceramic Substrate	LTCC HTCC	CPGA				
	Lead frame Substrate	DIP SOT/TSOP QFN QFP, LCC etc.	FC QFN				

Non-exhaustive list of technology and players examples

BONDING AND LITHOGRAPHY PROCESSES IN THE “MORE THAN MOORE” FIELD



Source: Bonding & Lithography Equipment Market for More than Moore Devices | www.yole.fr | © 2018

AGENDA

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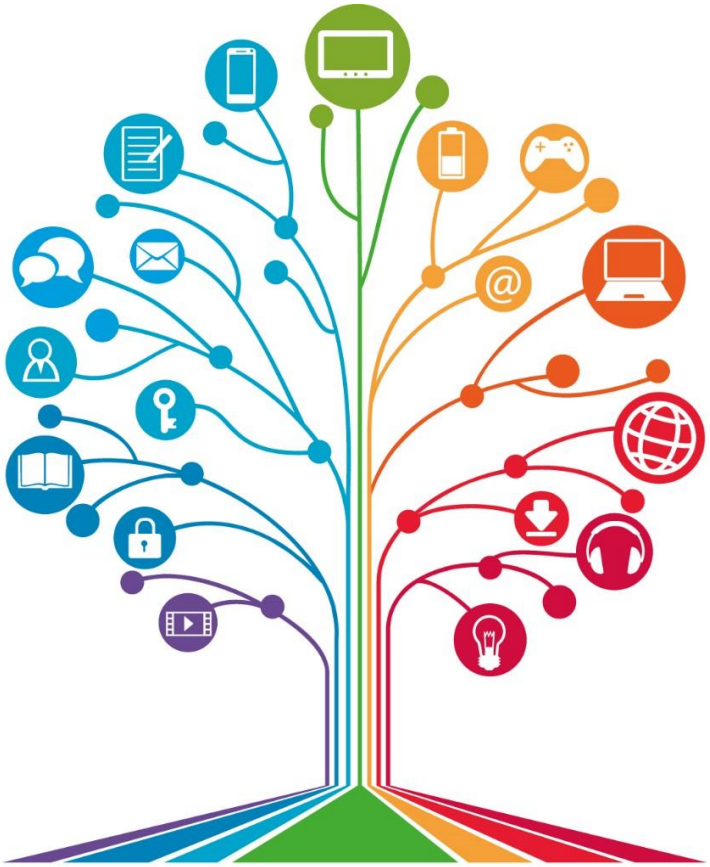
II. **Strategy SUSS 2025**

III. 9M and Preliminary Year End Results 2020

IV. Outlook

SUSS STRATEGY 2025: OVERVIEW



MARKET CONDITIONS

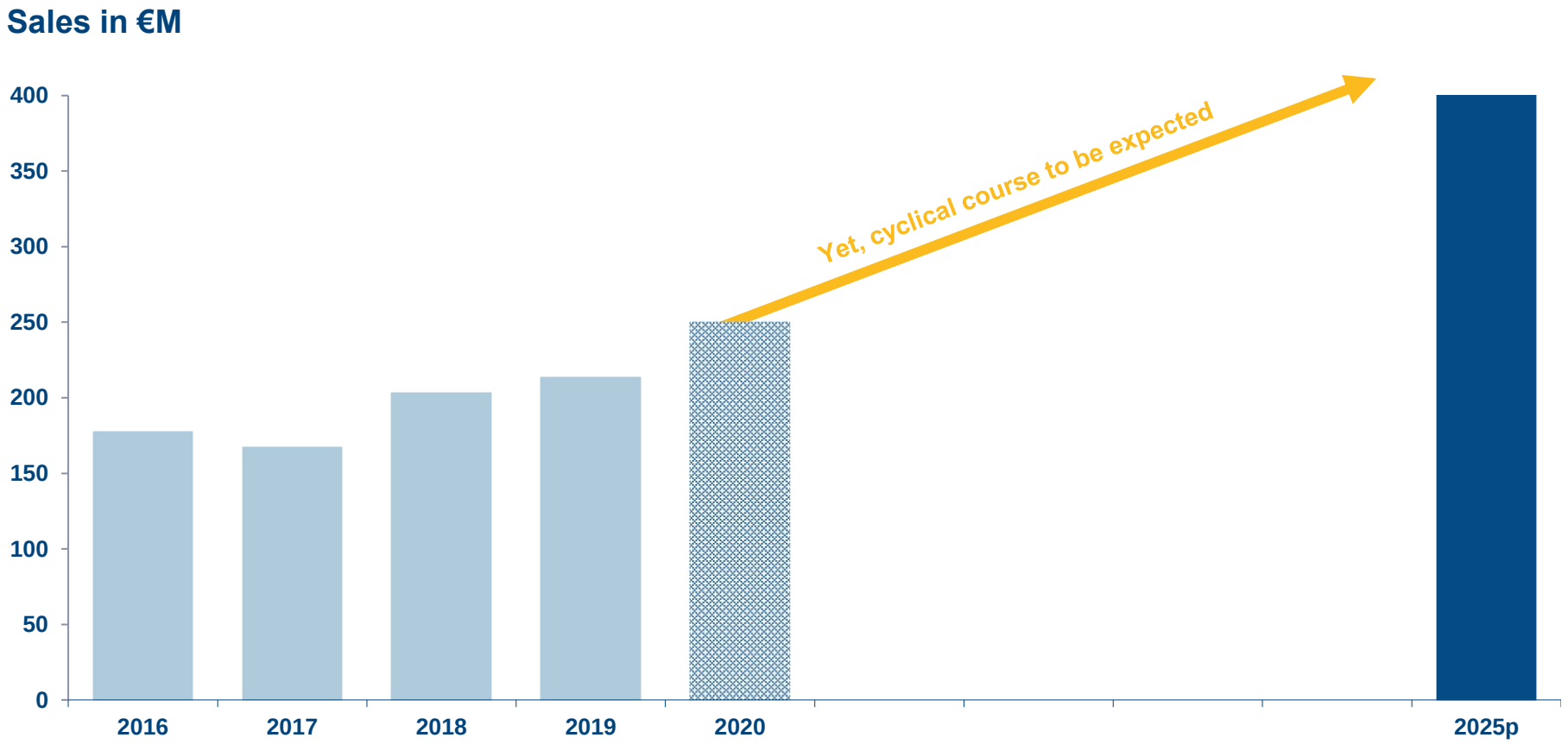
+ **Megatrends** are driving our business, great market outlook

+ **“More than Moore”** provides highly attractive growth potential

+ **5G, AI and IoT** are demanding broadband infrastructure
  - Home office equipment as short-term driver
  - Increased data volume with AI and IoT
  - Autonomous car generates 1 TB/day

+ Customers expect strong support in increasingly complex processes
  - Challenge but also an opportunity
  - SUSS is best positioned to play a strong role based on own strength → performance, reliability and flexibility!

SUSS 2025 STRATEGY: INCREASE IN SALES



Growth in the coming years through market growth, new products and market share gains

SUSS STRATEGY 2025: STRATEGIC TARGETS

Top-line growth

- Attractive products for maximum productivity and best-in-class yield
- Additional features to increase reliability

Improved operational performance and profitability

- Operational efficiency to be improved, programs are running
- Cost reduction through outsourcing and global purchasing
- Increase cash-flow by better inventory management

Focus on strategic growth areas

- Strong product offering already – short-term growth possible
- Platform design programs – longer term potential for margin increase

Goal 2025: € 400M with > 15% EBIT

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GENERAL BUSINESS UPDATE

Q4

Order entry **plus 21% yoy**

Orders increased
from € 61.5M to € 74.4M

Sales of around
€ 78M (prior year: € 82.7M)

FY 2020

Orders of **€ 281.1M compared to prior year with € 219.3M – plus 28% yoy**

Sales of around **€ 252M (prior year: € 213.8M)**
EBIT of **€ 20.9M** (prior year -€ 13.8M)
EBIT margin of **8.3%**
Expected Free Cashflow **> € 40M** (prior year -€ 36.9M)

Order backlog at December 31, 2020: € 120.1M – plus 29% yoy
Outlook for order entry (Q4 2020 + Q1 2021) increased from € 100 – 110M to more than € 120M

Book-to-Bill ratio >1

Good starting point for FY 2021

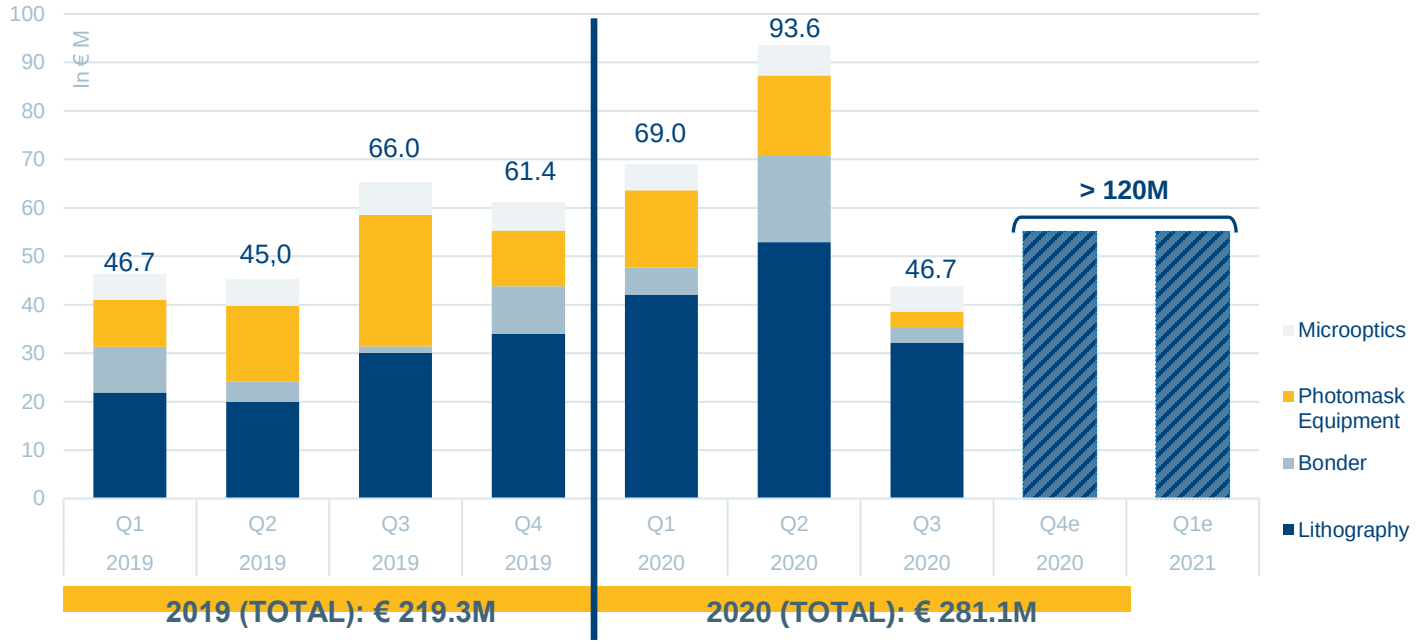
PRELIMINARY KEY GROUP FIGURES 2020

in € M	**FY 2020e**	FY 2019	Change
Order entry	281.1	219.3	+28.2%
Sales	252	213.8	~18%
EBIT	20.9	-13.8	+27.4M
EBIT margin	8.3%	-6.5%	+ 14.8% points
Adjusted EBIT	~25	0.5	+ € 24.5M
Adjusted EBIT-margin	9.9%	0.2%	+ 9.7% points
Free cash flow (in €)	> +40	-36.9	> +75M

+ Strong order entry FY 2020
+ Book-to-bill ratio: 1.12
+ Strong sales growth combined with a better GP margin resulted in a significantly improved EBIT (including closing cost of € 4M)
+ Free cash flow significantly improved by more than € 75M

ORDER ENTRY: STRONG QUARTERLY PERFORMANCE

ORDER ENTRY: SPLIT PER SEGMENT

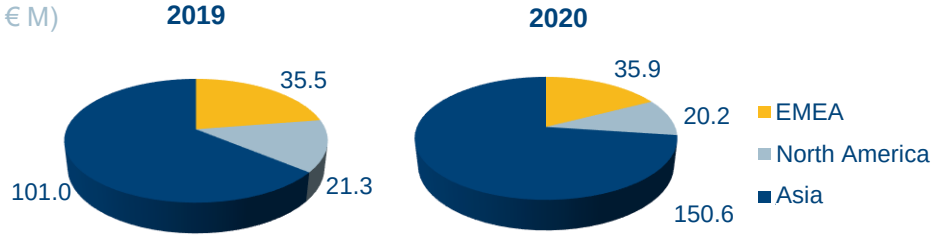


Comments:

- Overall the order entry level increased over the last years to an average of around and above € 60 M
- Order entry in Q2 includes a high volume Lithography order
- Increase in order entry for Bonders and Photomask Equipment expected in Q4 2020
- Order entry in Q4 expected to be higher than in Q3
- Increasing demand from Chinese customers is ongoing

ORDER ENTRY 9M: SPLIT PER REGION

(in € M)



Remarks for better understanding:

- Quarterly order intake since Q3/2019 is between €60 and €65 million. Extraordinary high order intake in Q2/2020 due to order accumulation of approx. “extra €30 million”
- Distribution of these “extra €30 million” from Q2/2020 over Q3 and Q4 would normalize the actual order flow
- The guidance provided above hints to an annual order intake of €240 million or a quarterly average of approx. €60 million

SEGMENT OVERVIEW 9M 2020

Lithography

in € M	**9m 2020**		9m 2019	
Sales	**97.8**		72.4	
GP (margin)	**29.7**	**(30.4%)**	16.1	(22.2%)
EBIT (margin)	**6.2**	**(6.3%)**	-8.1	(-11.2%)

+ Higher sales from mask aligners and coaters due to high volume orders from two major customers
+ Increased GP margin due to producivity gains
+ Closing cost Corona €5 M partly offset by sale of a written-off Scanner

Bonder

in € M	**9m 2020**		9m 2019	
Sales	**18.9**		17.2	
GP (margin)	**5.6**	**(29.6%)**	5.9	34.3 %
EBIT (margin)	**-0.6**	**(-3.2%)**	-0.7	(-4.1%)

+ Slight sales increase
+ Despite lower GP contribution EBIT loss could be improved to due lower opex
+ Further reduction of EBIT loss in Q4 expected

Photomask Equipment

in € M	**9m 2020**		9m 2019	
Sales	**40.0**		24.6	
GP (margin)	**16.7**	**(41.8%)**	9.2	(37.4%)
EBIT (margin)	**11.0**	**(27.5%)**	4.4	(17.9%)

+ Strong sales increase
+ Improved GP margin contribution and better fix cost coverage have a positive impact on EBIT / EBIT margin

Microoptics

in € M	**9m 2020**		9m 2019	
Sales	**16.8**		16.2	
GP (margin)	**4.9**	**(29.2%)**	6.6	(40.7%)
EBIT (margin)	**0.3**	**(1.8%)**	2.7	(16.7%)

+ Sales and GP impacted by Covid-19 (two months short-time work) lower demand from automotive OEMs
+ Additional cost due to quality problems with one key supplier
+ FX losses due to strong CHF

PRODUCTION SITES

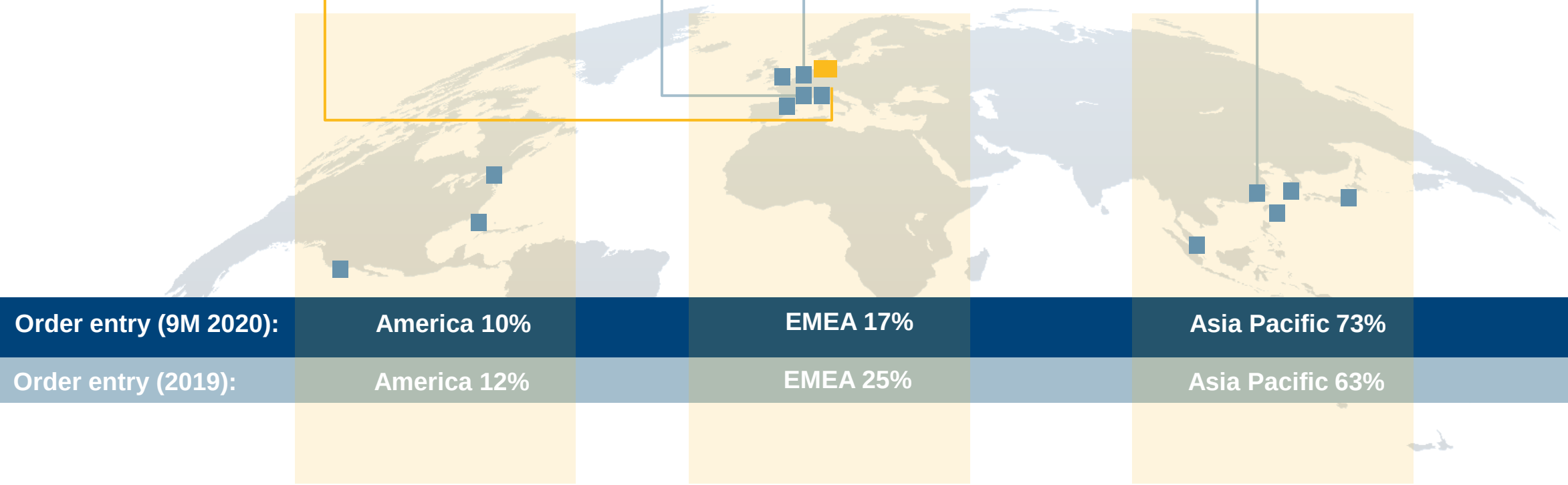
Garching / Munich
(SUSS MicroTec HQ)

Neuchatel
(Switzerland)

Sternenfels
(Germany)

Hsinchu
(Taiwan)

(HQ) Germany
SUSS sites



Order entry (9M 2020):	**America 10%**	**EMEA 17%**	**Asia Pacific 73%**
Order entry (2019):	**America 12%**	**EMEA 25%**	**Asia Pacific 63%**

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MARKETS ESTIMATES

Positive market outlook but impacted by COVID-19 uncertainties

Economic development not easy to forecast

Uncertain outlook with respect to US / China trade barriers

BUT

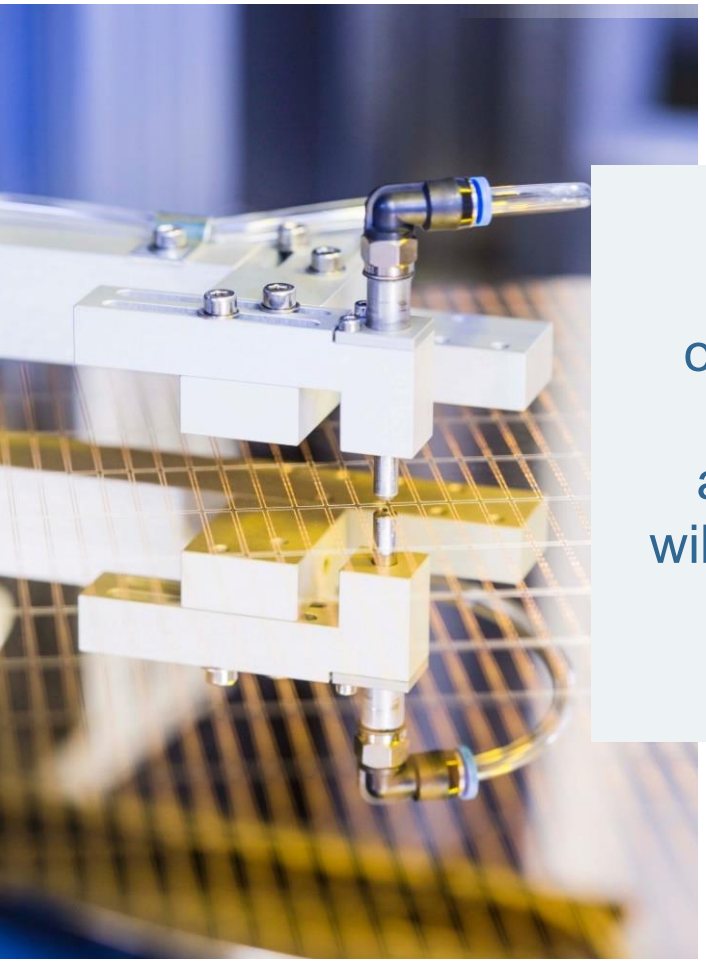
Clear signal for need to invest in broadband communication systems

Significant increase in demand from telecom market

Future demand driven by emerging technologies, such as 5G, IoT, high-performance computing, augmented reality, artificial intelligence, autonomous driving, etc.

Customers still pushing for shorter delivery times

OUTLOOK



Expected order entry for Q4/2020 and Q1/2021 will be more than
€ 120M

Preliminary Sales
€ 252M

Preliminary EBIT margin
8.3%


Thank you!